

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10581395								
<b>Filing Date:</b>	14-Aug-2008								
<b>Title of Invention:</b>  Chip Scale Package and Method of Assembling the Same									
<b>First Named Inventor/Applicant Name:</b> Hien Boon Tan									
<b>Filer:</b> Carl Joseph Pellegrini/ruth swanson									
<b>Attorney Docket Number:</b> Q78657									
Filed as Large Entity									
<b>U.S. National Stage under 35 USC 371 Filing Fees</b>									
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 35%; padding: 2px;">Description</th> <th style="width: 15%; padding: 2px;">Fee Code</th> <th style="width: 15%; padding: 2px;">Quantity</th> <th style="width: 15%; padding: 2px;">Amount</th> <th style="width: 15%; padding: 2px;">Sub-Total in USD(\$)</th> </tr> </thead> </table>					Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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<b>Basic Filing:</b>									
<b>Pages:</b>									
<b>Claims:</b>									
<b>Miscellaneous-Filing:</b>									
<b>Petition:</b>									
<b>Patent-Appeals-and-Interference:</b>									
<b>Post-Allowance-and-Post-Issuance:</b>									
<b>Extension-of-Time:</b>									
Extension - 2 months with \$0 paid		1252	1	490					
		490							

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Miscellaneous:</b>				
<b>Total in USD (\$)</b>				<b>490</b>